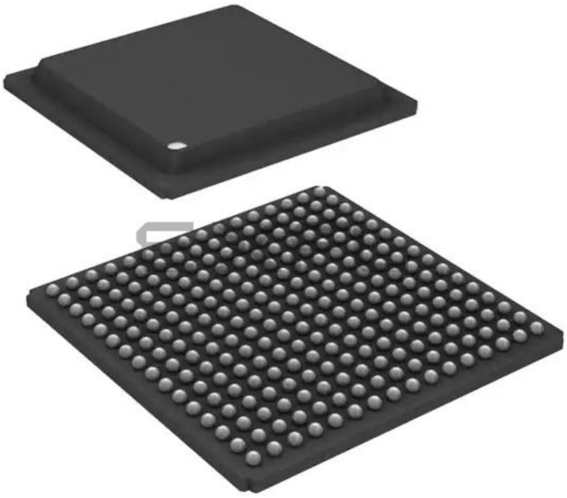

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	50MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (1)
SATA	-
USB	USB 1.x (1)
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 95°C (TA)
Security Features	-
Package / Case	256-BBGA
Supplier Device Package	256-PBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmc850dslczq50bu

Table 6. Bus Operation Timing [1] (continued)

Num	Characteristic	50 MHz		66 MHz		80 MHz		FFACT	Cap Load (default 50 pF)	Unit
		Min	Max	Min	Max	Min	Max			
B9	CLKOUT to A[6–31] RD/WR, BURST, D[0–31], DP[0–3], TSIZ[0–1], REG, RSV, AT[0–3], PTR high-Z	5.00	11.75	7.58	14.33	6.25	13.00	0.250	50.00	ns
B11	CLKOUT to TS, BB assertion	5.00	11.00	7.58	13.58	6.25	12.25	0.250	50.00	ns
B11a	CLKOUT to TA, BI assertion, (When driven by the memory controller or PCMCIA interface)	2.50	9.25	2.50	9.25	2.50	9.25	—	50.00	ns
B12	CLKOUT to TS, BB negation	5.00	11.75	7.58	14.33	6.25	13.00	0.250	50.00	ns
B12a	CLKOUT to TA, BI negation (when driven by the memory controller or PCMCIA interface)	2.50	11.00	2.50	11.00	2.50	11.00	—	50.00	ns
B13	CLKOUT to TS, BB high-Z	5.00	19.00	7.58	21.58	6.25	20.25	0.250	50.00	ns
B13a	CLKOUT to TA, BI high-Z, (when driven by the memory controller or PCMCIA interface)	2.50	15.00	2.50	15.00	2.50	15.00	—	50.00	ns
B14	CLKOUT to TEA assertion	2.50	10.00	2.50	10.00	2.50	10.00	—	50.00	ns
B15	CLKOUT to TEA high-Z	2.50	15.00	2.50	15.00	2.50	15.00	—	50.00	ns
B16	TA, BI valid to CLKOUT(setup time) [5]	9.75	—	9.75	—	9.75	—	—	50.00	ns
B16a	TEA, KR, RETRY, valid to CLKOUT (setup time) [5]	10.00	—	10.00	—	10.00	—	—	50.00	ns
B16b	BB, BG, BR valid to CLKOUT (setup time) [6]	8.50	—	8.50	—	8.50	—	—	50.00	ns
B17	CLKOUT to TA, TEA, BI, BB, BG, BR valid (Hold time).[5]	1.00	—	1.00	—	1.00	—	—	50.00	ns
B17a	CLKOUT to KR, RETRY, except TEA valid (hold time)	2.00	—	2.00	—	2.00	—	—	50.00	ns
B18	D[0–31], DP[0–3] valid to CLKOUT rising edge (setup time) [7]	6.00	—	6.00	—	6.00	—	—	50.00	ns
B19	CLKOUT rising edge to D[0–31], DP[0–3] valid (hold time) [7]	1.00	—	1.00	—	1.00	—	—	50.00	ns
B20	D[0–31], DP[0–3] valid to CLKOUT falling edge (setup time) [8]	4.00	—	4.00	—	4.00	—	—	50.00	ns
B21	CLKOUT falling edge to D[0–31], DP[0–3] valid (hold time) [8]	2.00	—	2.00	—	2.00	—	—	—	—

Table 6. Bus Operation Timing [1] (continued)

Num	Characteristic	50 MHz		66 MHz		80 MHz		FFACT	Cap Load (default 50 pF)	Unit
		Min	Max	Min	Max	Min	Max			
B28c	CLKOUT falling edge to WE[0–3] negated GPCM write access TRLX = 0,1 CSNT = 1 write access TRLX = 0, CSNT = 1, EBDF = 1	7.00	14.00	11.00	18.00	9.00	16.00	0.375	50.00	ns
B28d	CLKOUT falling edge to CS negated GPCM write access TRLX = 0,1 CSNT = 1, ACS = 10 or ACS = 11, EBDF = 1	—	14.00	—	18.00	—	16.00	0.375	50.00	ns
B29	WE[0–3] negated to D[0–31], DP[0–3] high-Z GPCM write access, CSNT = 0	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B29a	WE[0–3] negated to D[0–31], DP[0–3] high-Z GPCM write access, TRLX = 0 CSNT = 1, EBDF = 0	8.00	—	13.00	—	11.00	—	0.500	50.00	ns
B29b	CS negated to D[0–31], DP[0–3], high-Z GPCM write access, ACS = 00, TRLX = 0 & CSNT = 0	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B29c	CS negated to D[0–31], DP[0–3] high-Z GPCM write access, TRLX = 0, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 0	8.00	—	13.00	—	11.00	—	0.500	50.00	ns
B29d	WE[0–3] negated to D[0–31], DP[0–3] high-Z GPCM write access, TRLX = 1, CSNT = 1, EBDF = 0	28.00	—	43.00	—	36.00	—	1.500	50.00	ns
B29e	CS negated to D[0–31], DP[0–3] high-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 0	28.00	—	43.00	—	36.00	—	1.500	50.00	ns
B29f	WE[0–3] negated to D[0–31], DP[0–3] high-Z GPCM write access TRLX = 0, CSNT = 1, EBDF = 1	5.00	—	9.00	—	7.00	—	0.375	50.00	ns
B29g	CS negated to D[0–31], DP[0–3] high-Z GPCM write access TRLX = 0, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 1	5.00	—	9.00	—	7.00	—	0.375	50.00	ns

Table 6. Bus Operation Timing [1] (continued)

Num	Characteristic	50 MHz		66 MHz		80 MHz		FFACT	Cap Load (default 50 pF)	Unit
		Min	Max	Min	Max	Min	Max			
B29h	WE[0–3] negated to D[0–31], DP[0–3] high-Z GPCM write access TRLX = 0, CSNT = 1, EBDF = 1	25.00	—	39.00	—	31.00	—	1.375	50.00	ns
B29i	CS negated to D[0–31], DP[0–3] high-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 1	25.00	—	39.00	—	31.00	—	1.375	50.00	ns
B30	CS, WE[0–3] negated to A[6–31] invalid GPCM write access [9]	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B30a	WE[0–3] negated to A[6–31] invalid GPCM write access, TRLX = 0, CSNT = 1, CS negated to A[6–31] invalid GPCM write access TRLX = 0, CSNT =1, ACS = 10 or ACS = 11, EBDF = 0	8.00	—	13.00	—	11.00	—	0.500	50.00	ns
B30b	WE[0–3] negated to A[6–31] invalid GPCM write access, TRLX = 1, CSNT = 1. CS negated to A[6–31] Invalid GPCM write access TRLX = 1, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 0	28.00	—	43.00	—	36.00	—	1.500	50.00	ns
B30c	WE[0–3] negated to A[6–31] invalid GPCM write access, TRLX = 0, CSNT = 1. CS negated to A[6–31] invalid GPCM write access, TRLX = 0, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 1	5.00	—	8.00	—	6.00	—	0.375	50.00	ns
B30d	WE[0–3] negated to A[6–31] invalid GPCM write access TRLX = 1, CSNT =1, CS negated to A[6–31] invalid GPCM write access TRLX = 1, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 1	25.00	—	39.00	—	31.00	—	1.375	50.00	ns

Table 6. Bus Operation Timing [1] (continued)

Num	Characteristic	50 MHz		66 MHz		80 MHz		FFACT	Cap Load (default 50 pF)	Unit
		Min	Max	Min	Max	Min	Max			
B33a	CLKOUT rising edge to GPL valid - as requested by control bit GxT3 in the corresponding word in the UPM	5.00	12.00	8.00	14.00	6.00	13.00	0.250	50.00	ns
B34	A[6–31] and D[0–31] to $\overline{CS}$ valid - as requested by control bit CST4 in the corresponding word in the UPM	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B34a	A[6–31] and D[0–31] to $\overline{CS}$ valid - as requested by control bit CST1 in the corresponding word in the UPM	8.00	—	13.00	—	11.00	—	0.500	50.00	ns
B34b	A[6–31] and D[0–31] to $\overline{CS}$ valid - as requested by CST2 in the corresponding word in UPM	13.00	—	21.00	—	17.00	—	0.750	50.00	ns
B35	A[6–31] to $\overline{CS}$ valid - as requested by control bit BST4 in the corresponding word in UPM	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B35a	A[6–31] and D[0–31] to $\overline{BS}$ valid - as requested by BST1 in the corresponding word in the UPM	8.00	—	13.00	—	11.00	—	0.500	50.00	ns
B35b	A[6–31] and D[0–31] to $\overline{BS}$ valid - as requested by control bit BST2 in the corresponding word in the UPM	13.00	—	21.00	—	17.00	—	0.750	50.00	ns
B36	A[6–31] and D[0–31] to GPL valid - as requested by control bit GxT4 in the corresponding word in the UPM	3.00	—	6.00	—	4.00	—	0.250	50.00	ns
B37	UPWAIT valid to CLKOUT falling edge [10]	6.00	—	6.00	—	6.00	—	—	50.00	ns
B38	CLKOUT falling edge to UPWAIT valid [10]	1.00	—	1.00	—	1.00	—	—	50.00	ns
B39	$\overline{AS}$ valid to CLKOUT rising edge [11]	7.00	—	7.00	—	7.00	—	—	50.00	ns
B40	A[6–31], TSIZ[0–1], RD/$\overline{WR}$, $\overline{BURST}$, valid to CLKOUT rising edge.	7.00	—	7.00	—	7.00	—	—	50.00	ns
B41	$\overline{TS}$ valid to CLKOUT rising edge (setup time)	7.00	—	7.00	—	7.00	—	—	50.00	ns

Figure 13 through Figure 15 provide the timing for the external bus write controlled by various GPCM factors.

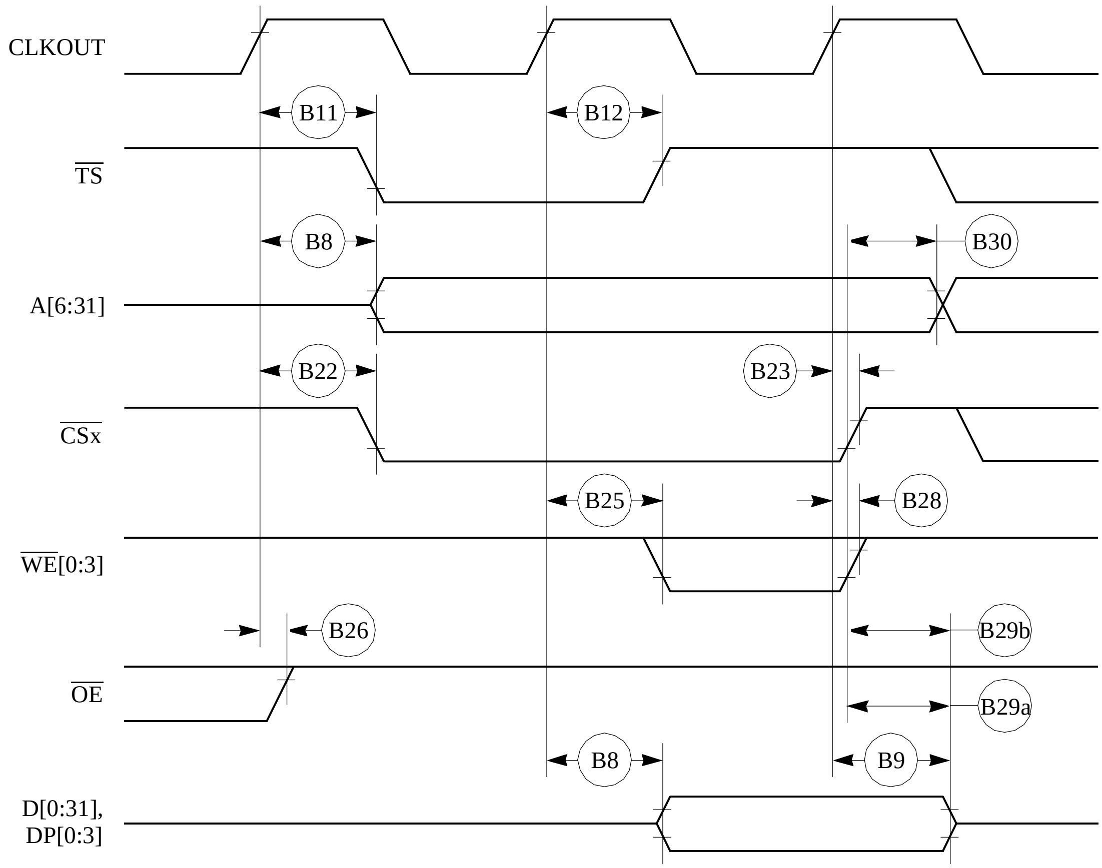


Figure 13. External Bus Write Timing (GPCM Controlled—TRLX = 0, CSNT = 0)

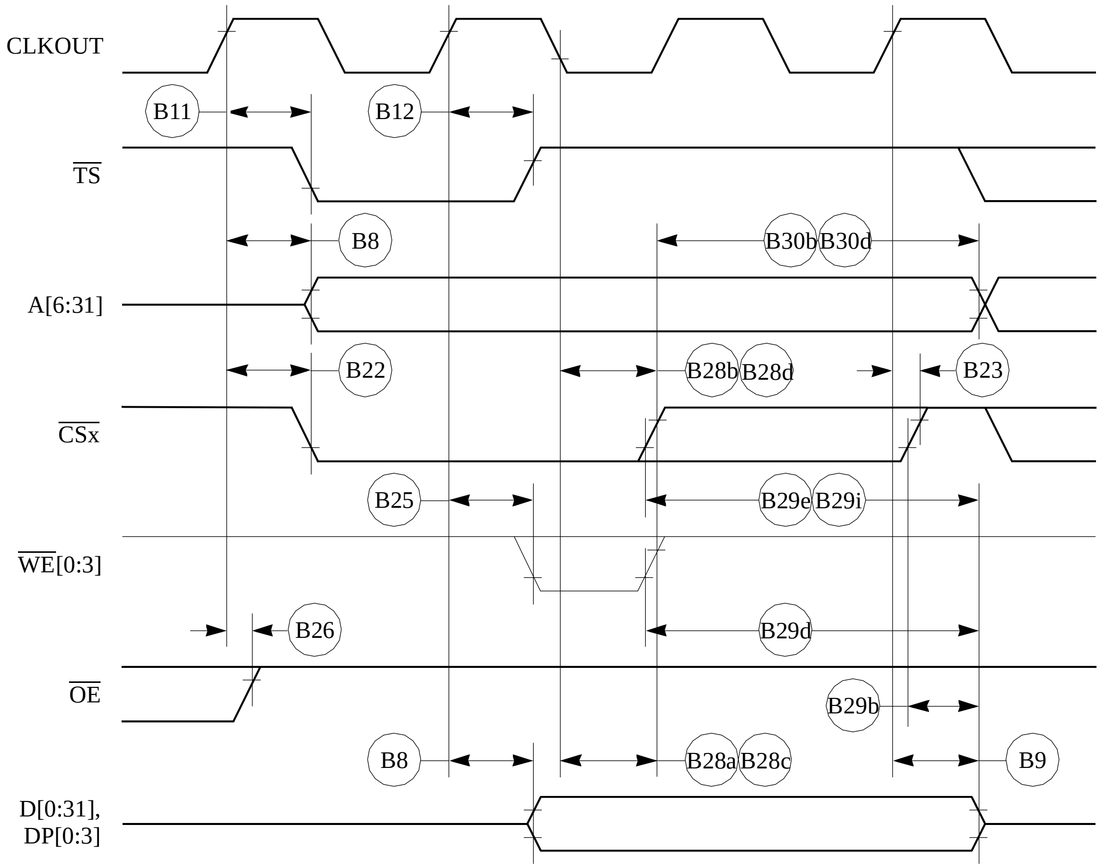


Figure 15. External Bus Write Timing (GPCM Controlled—TRLX = 1, CSNT = 1)

Table 7 provides interrupt timing for the MPC850.

Table 7. Interrupt Timing

Num	Characteristic [1]	50 MHz		66MHz		80 MHz		Unit
		Min	Max	Min	Max	Min	Max	
I39	$\overline{\text{IRQx}}$ valid to CLKOUT rising edge (set up time)	6.00	—	6.00	—	6.00	—	ns
I40	$\overline{\text{IRQx}}$ hold time after CLKOUT.	2.00	—	2.00	—	2.00	—	ns
I41	$\overline{\text{IRQx}}$ pulse width low	3.00	—	3.00	—	3.00	—	ns
I42	$\overline{\text{IRQx}}$ pulse width high	3.00	—	3.00	—	3.00	—	ns
I43	$\overline{\text{IRQx}}$ edge-to-edge time	80.00	—	121.0	—	100.0	—	ns

[1] The timings I39 and I40 describe the testing conditions under which the $\overline{\text{IRQ}}$ lines are tested when being defined as level sensitive. The $\overline{\text{IRQ}}$ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT.

The timings I41, I42, and I43 are specified to allow the correct function of the $\overline{\text{IRQ}}$ lines detection circuitry, and has no direct relation with the total system interrupt latency that the MPC850 is able to support

Figure 22 provides the interrupt detection timing for the external level-sensitive lines.

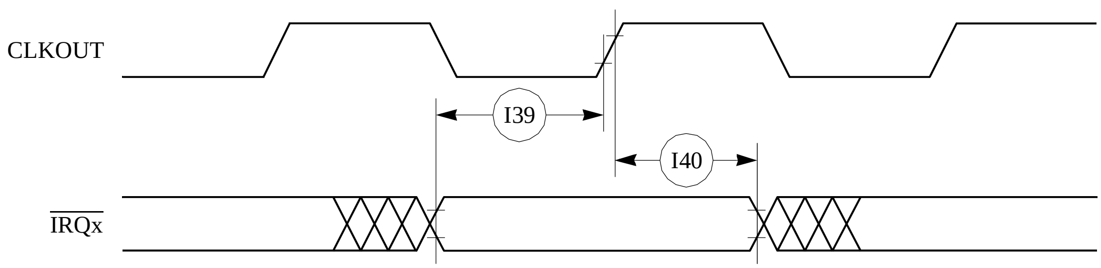


Figure 22. Interrupt Detection Timing for External Level Sensitive Lines

Figure 23 provides the interrupt detection timing for the external edge-sensitive lines.

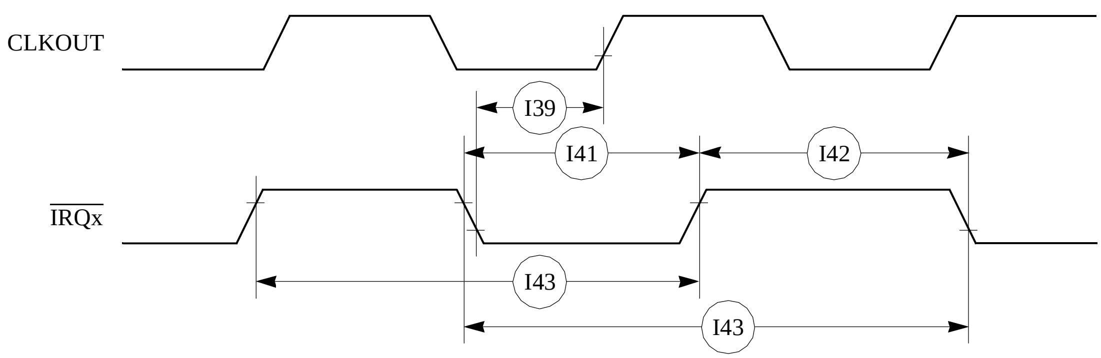


Figure 23. Interrupt Detection Timing for External Edge Sensitive Lines

Figure 25 provides the PCMCIA access cycle timing for the external bus write.

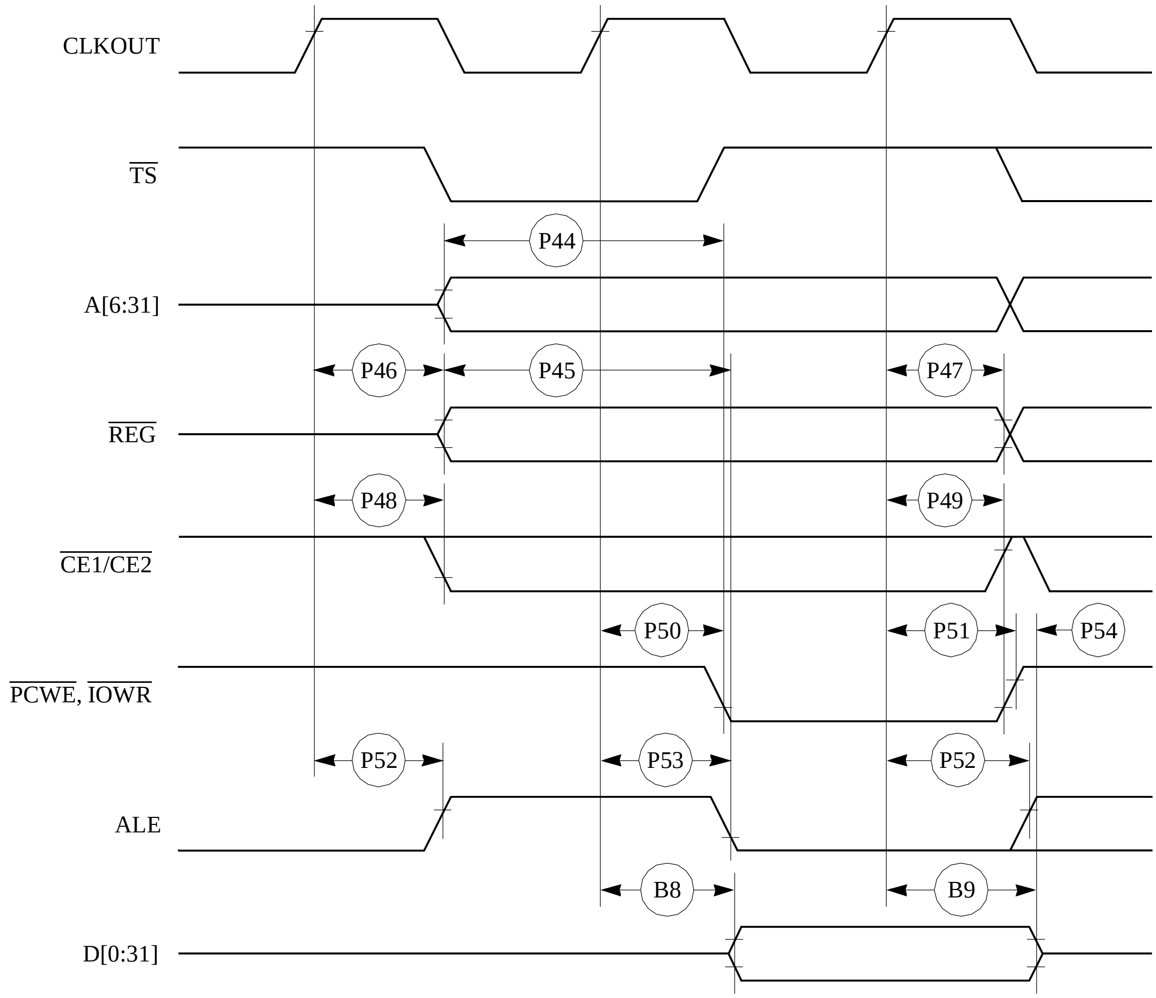


Figure 25. PCMCIA Access Cycles Timing External Bus Write

Figure 26 provides the PCMCIA WAIT signals detection timing.

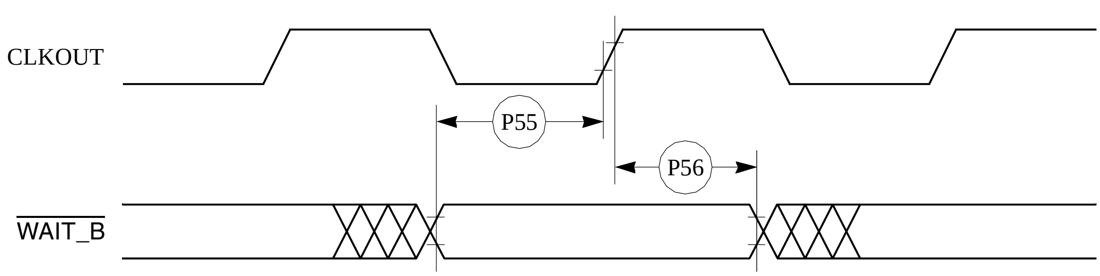


Figure 26. PCMCIA WAIT Signal Detection Timing

Figure 31 shows the reset timing for the data bus configuration.

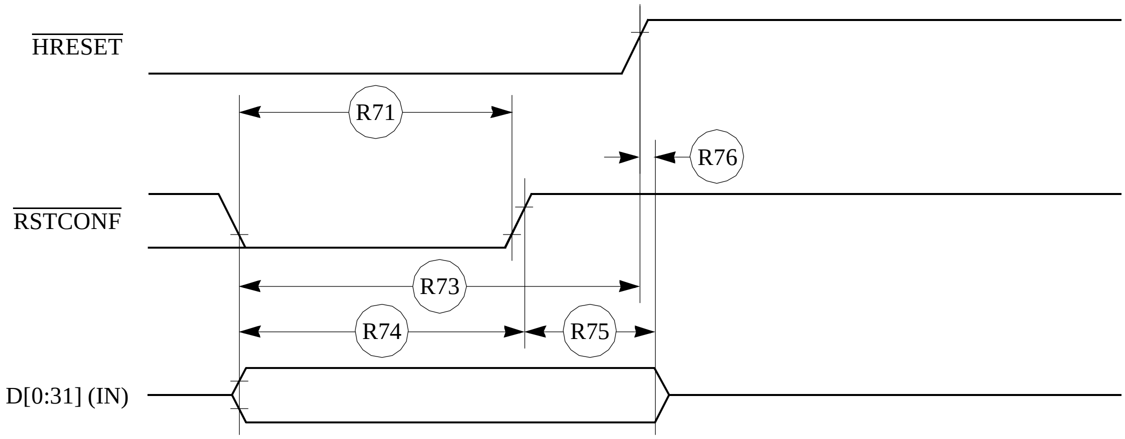


Figure 31. Reset Timing—Configuration from Data Bus

Figure 32 provides the reset timing for the data bus weak drive during configuration.

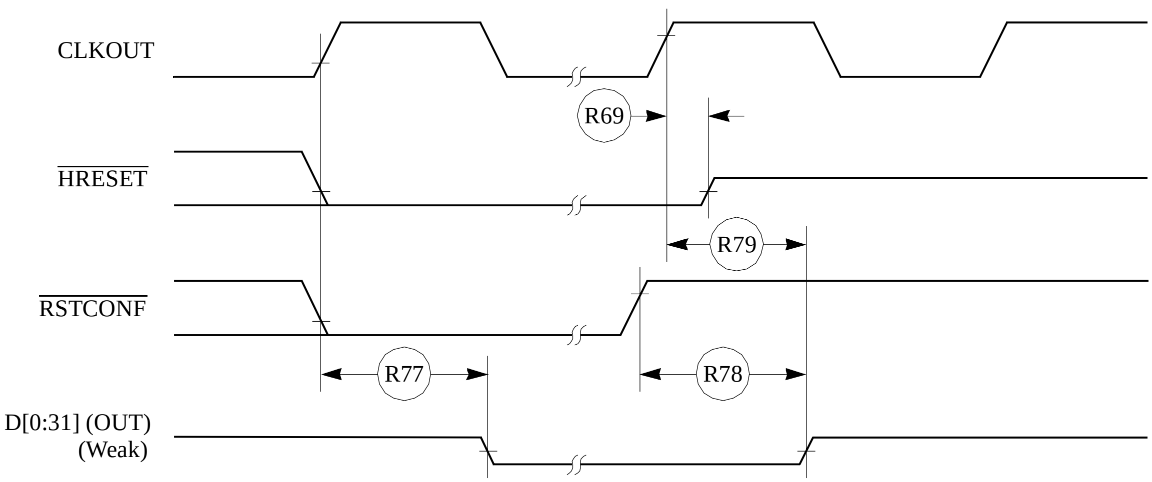


Figure 32. Reset Timing—Data Bus Weak Drive during Configuration

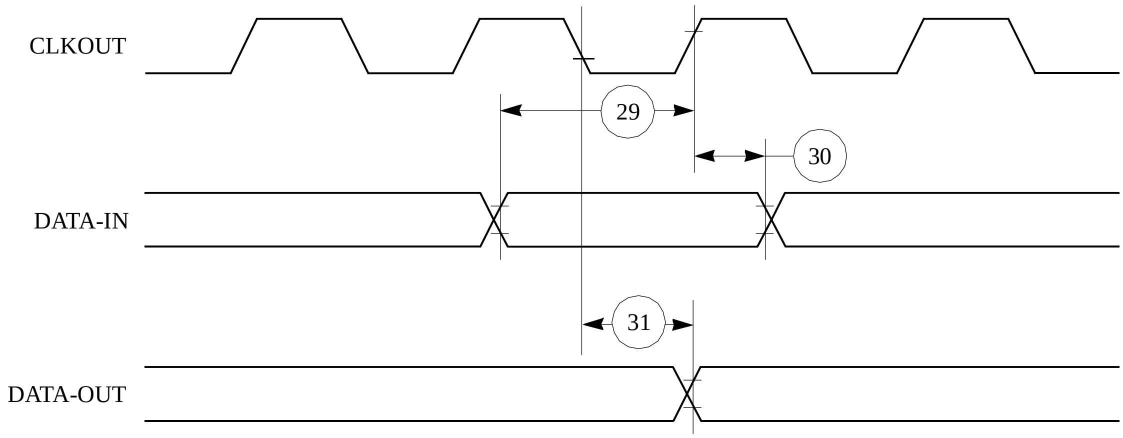


Figure 38. Parallel I/O Data-In/Data-Out Timing Diagram

8.2 IDMA Controller AC Electrical Specifications

Table 14 provides the IDMA controller timings as shown in Figure 39 to Figure 42.

Table 14. IDMA Controller Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
40	$\overline{\text{DREQ}}$ setup time to clock high	7.00	—	ns
41	$\overline{\text{DREQ}}$ hold time from clock high	3.00	—	ns
42	$\overline{\text{SDACK}}$ assertion delay from clock high	—	12.00	ns
43	$\overline{\text{SDACK}}$ negation delay from clock low	—	12.00	ns
44	$\overline{\text{SDACK}}$ negation delay from $\overline{\text{TA}}$ low	—	20.00	ns
45	$\overline{\text{SDACK}}$ negation delay from clock high	—	15.00	ns
46	$\overline{\text{TA}}$ assertion to falling edge of the clock setup time (applies to external $\overline{\text{TA}}$)	7.00	—	ns

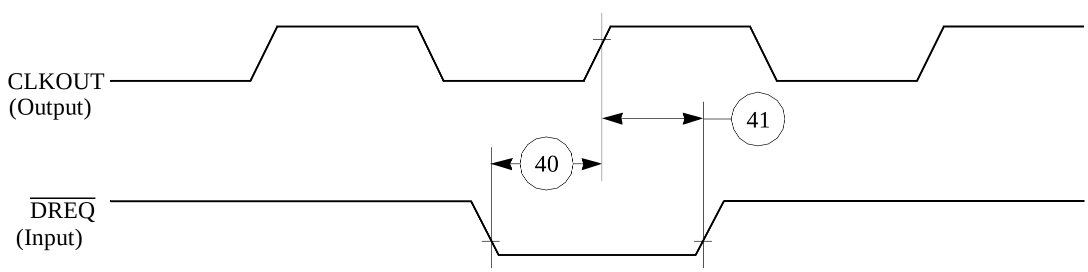


Figure 39. IDMA External Requests Timing Diagram

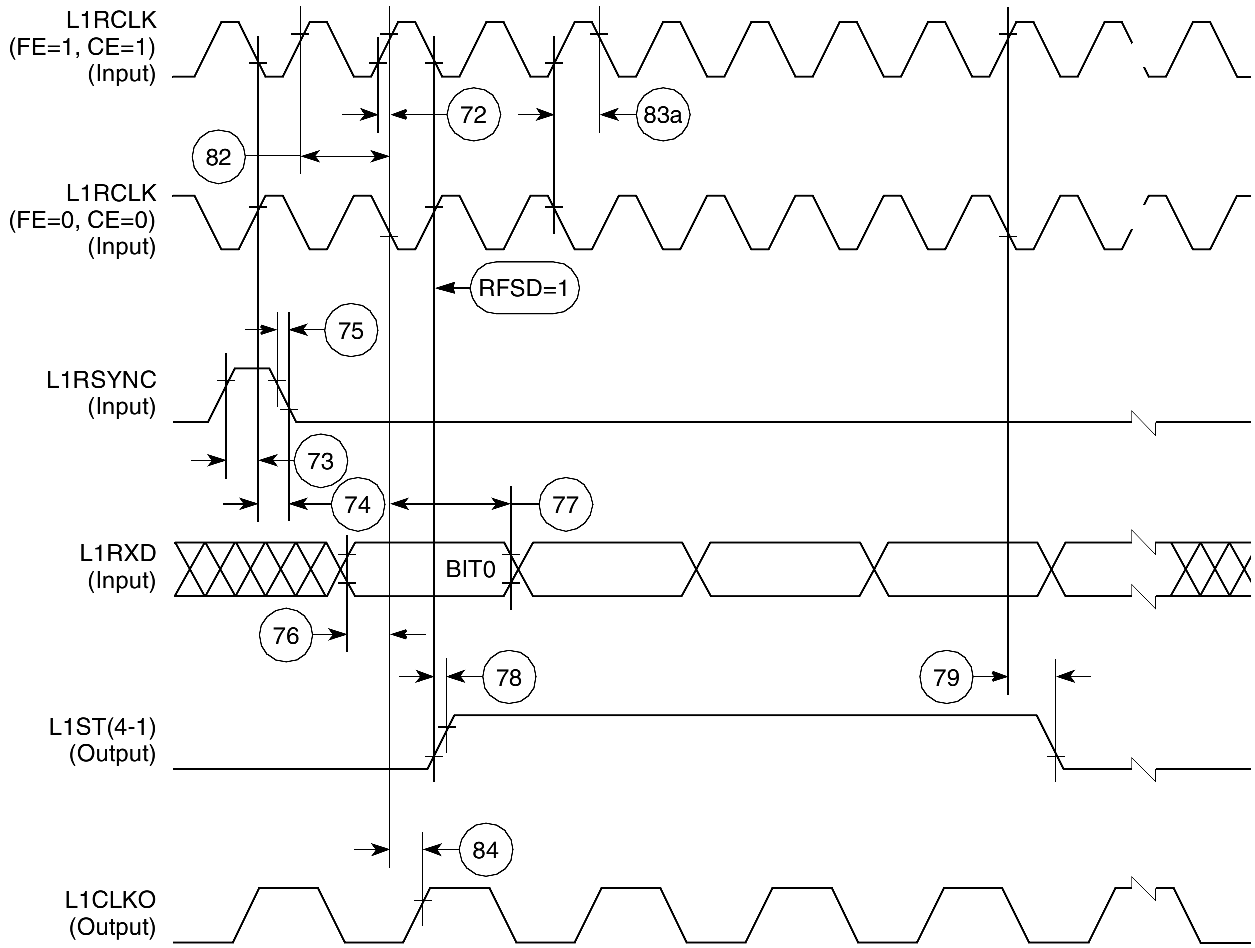


Figure 46. SI Receive Timing with Double-Speed Clocking (DSC = 1)

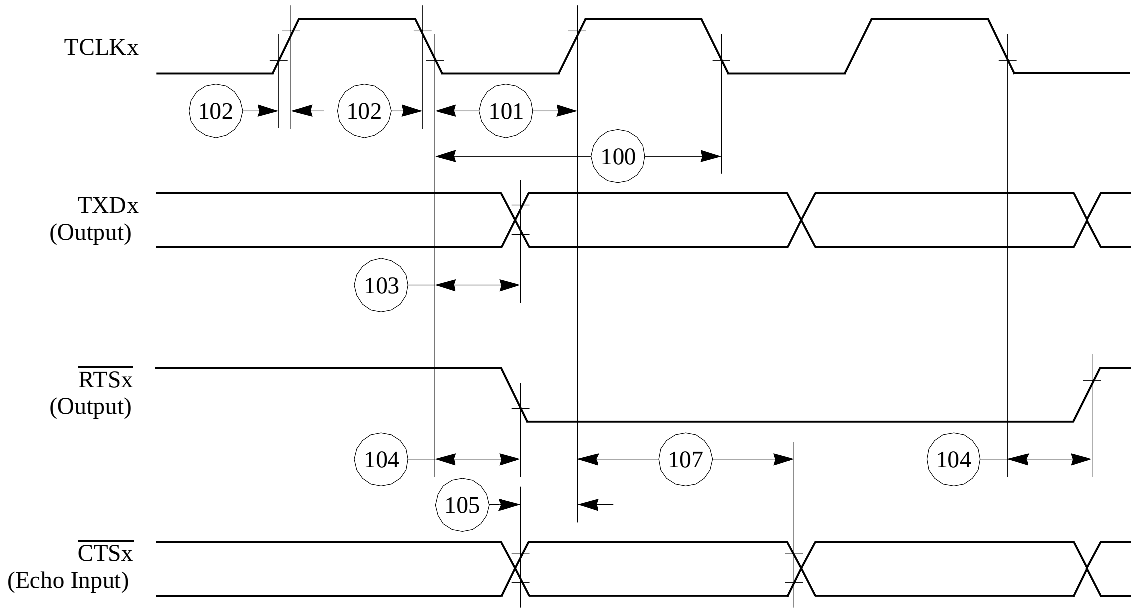


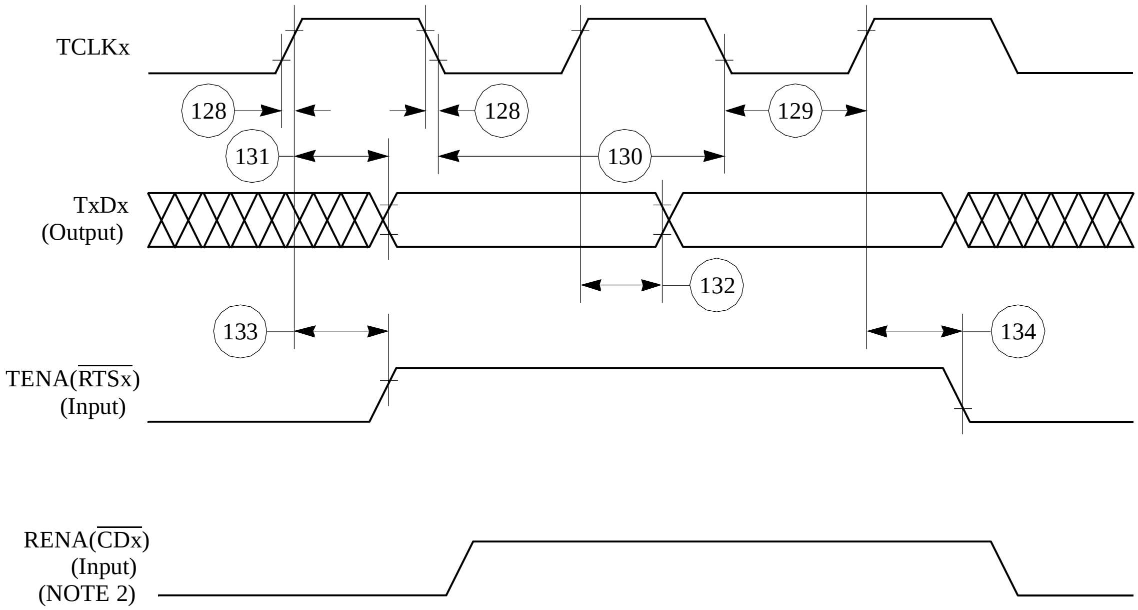
Figure 52. HDLC Bus Timing Diagram

8.7 Ethernet Electrical Specifications

Table 20 provides the Ethernet timings as shown in Figure 53 to Figure 55.

Table 20. Ethernet Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
120	CLSN width high	40.00	—	ns
121	RCLKx rise/fall time (x = 2, 3 for all specs in this table)	—	15.00	ns
122	RCLKx width low	40.00	—	ns
123	RCLKx clock period [1]	80.00	120.00	ns
124	RXDx setup time	20.00	—	ns
125	RXDx hold time	5.00	—	ns
126	RENA active delay (from RCLKx rising edge of the last data bit)	10.00	—	ns
127	RENA width low	100.00	—	ns
128	TCLKx rise/fall time	—	15.00	ns
129	TCLKx width low	40.00	—	ns
130	TCLKx clock period[1]	99.00	101.00	ns
131	TXDx active delay (from TCLKx rising edge)	10.00	50.00	ns
132	TXDx inactive delay (from TCLKx rising edge)	10.00	50.00	ns
133	TENA active delay (from TCLKx rising edge)	10.00	50.00	ns



NOTES:
1. Transmit clock invert (TCI) bit in GSMR is set.
2. If RENA is deasserted before TENA, or RENA is not asserted at all during transmit, then the CSL bit is set in the buffer descriptor at the end of the frame transmission.

Figure 55. Ethernet Transmit Timing Diagram

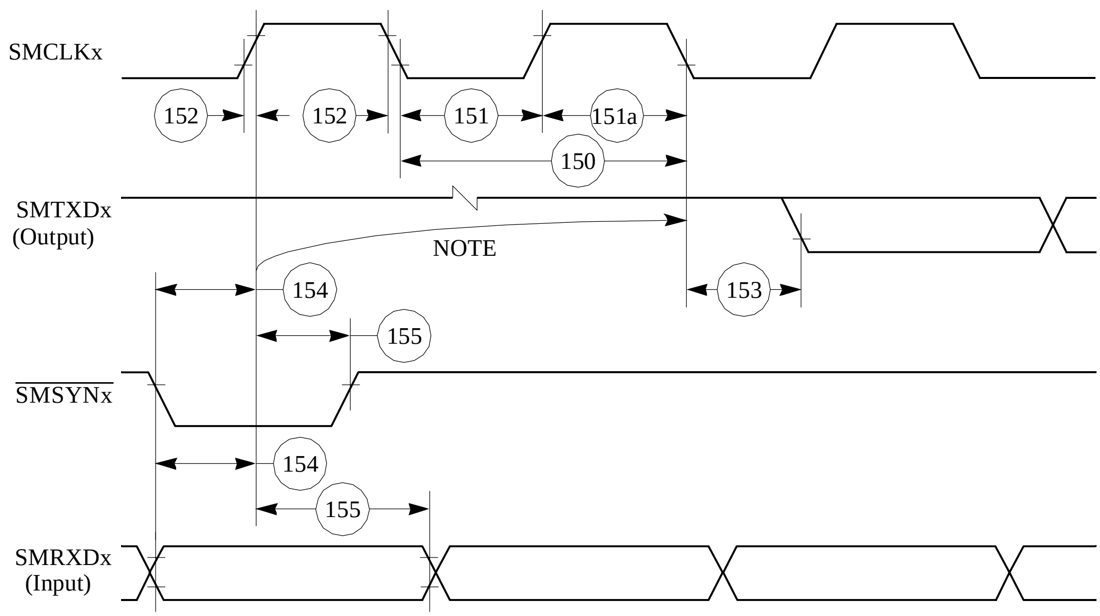
8.8 SMC Transparent AC Electrical Specifications

Figure 21 provides the SMC transparent timings as shown in Figure 56.

Table 21. Serial Management Controller Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
150	SMCLKx clock period [1]	100.00	—	ns
151	SMCLKx width low	50.00	—	ns
151a	SMCLKx width high	50.00	—	ns
152	SMCLKx rise/fall time	—	15.00	ns
153	SMTXDx active delay (from SMCLKx falling edge)	10.00	50.00	ns
154	SMRXDx/SMSYNx setup time	20.00	—	ns
155	SMRXDx/SMSYNx hold time	5.00	—	ns

[1] The ratio SyncCLK/SMCLKx must be greater or equal to 2/1.



NOTE:
1. This delay is equal to an integer number of character-length clocks.

Figure 56. SMC Transparent Timing Diagram

8.9 SPI Master AC Electrical Specifications

Table 22 provides the SPI master timings as shown in Figure 57 and Figure 58.

Table 22. SPI Master Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
160	MASTER cycle time	4	1024	t_{cyc}
161	MASTER clock (SCK) high or low time	2	512	t_{cyc}
162	MASTER data setup time (inputs)	50.00	—	ns
163	Master data hold time (inputs)	0.00	—	ns
164	Master data valid (after SCK edge)	—	20.00	ns
165	Master data hold time (outputs)	0.00	—	ns
166	Rise time output	—	15.00	ns
167	Fall time output	—	15.00	ns

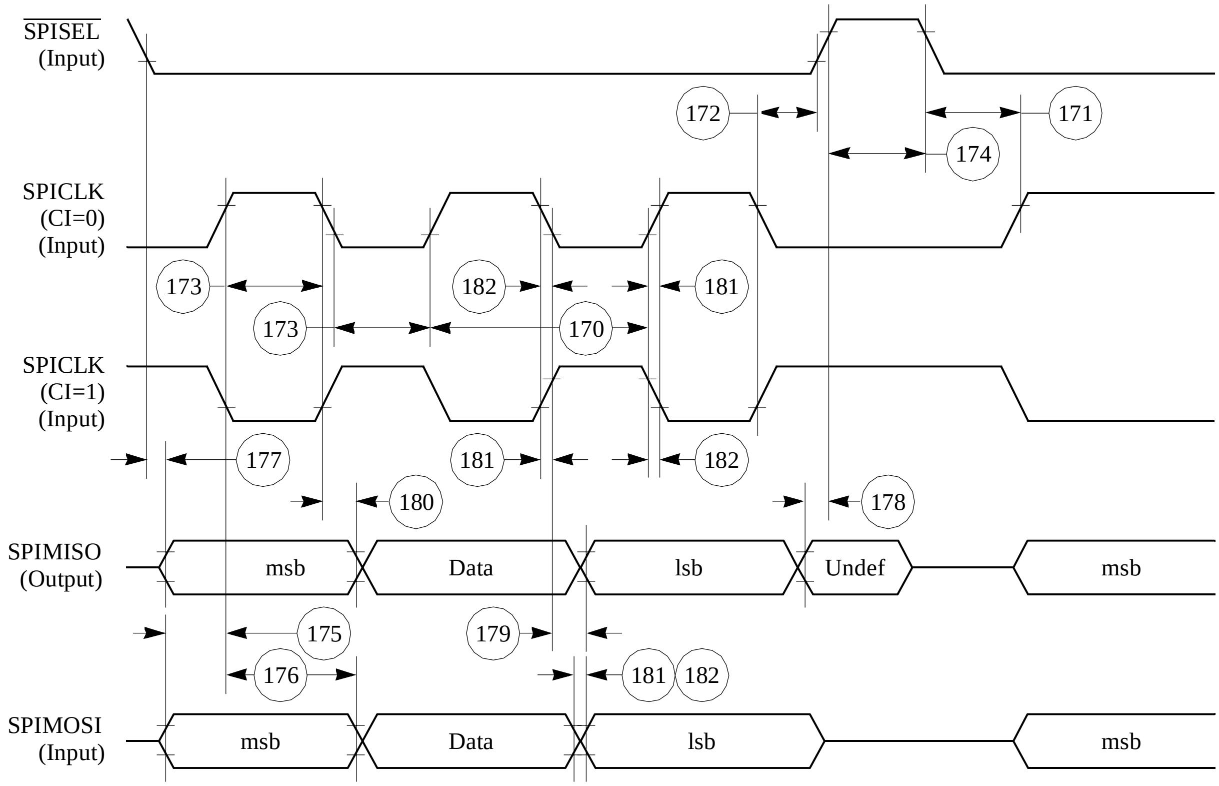


Figure 59. SPI Slave (CP = 0) Timing Diagram

9 Mechanical Data and Ordering Information

Table 26 provides information on the MPC850 derivative devices.

Table 26. MPC850 Family Derivatives

Device	Ethernet Support	Number of SCCs [1]	32-Channel HDLC Support	64-Channel HDLC Support [2]
MPC850	N/A	One	N/A	N/A
MPC850DE	Yes	Two	N/A	N/A
MPC850SR	Yes	Two	N/A	Yes
MPC850DSL	Yes	Two	No	No

[1] Serial Communication Controller (SCC)

[2] 50 MHz version supports 64 time slots on a time division multiplexed line using one SCC

Table 27 identifies the packages and operating frequencies available for the MPC850.

Table 27. MPC850 Package/Frequency/Availability

Package Type	Frequency (MHz)	Temperature (Tj)	Order Number
256-Lead Plastic Ball Grid Array (ZT suffix)	50	0°C to 95°C	XPC850ZT50BU XPC850DEZT50BU XPC850SRZT50BU XPC850DSLZT50BU
	66	0°C to 95°C	XPC850ZT66BU XPC850DEZT66BU XPC850SRZT66BU
	80	0°C to 95°C	XPC850ZT80BU XPC850DEZT80BU XPC850SRZT80BU
256-Lead Plastic Ball Grid Array (CZT suffix)	50	-40°C to 95°C	XPC850CZT50BU XPC850DECZT50BU XPC850SRCZT50BU XPC850DSLCZT50BU
	66		XPC850CZT66BU XPC850DECZT66BU XPC850SRCZT66BU
	80		XPC850CZT80B XPC850DECZT80B XPC850SRCZT80B

9.1 Pin Assignments and Mechanical Dimensions of the PBGA

The original pin numbering of the MPC850 conformed to a Freescale proprietary pin numbering scheme that has since been replaced by the JEDEC pin numbering standard for this package type. To support

Figure 63 shows the JEDEC pinout of the PBGA package as viewed from the top surface.

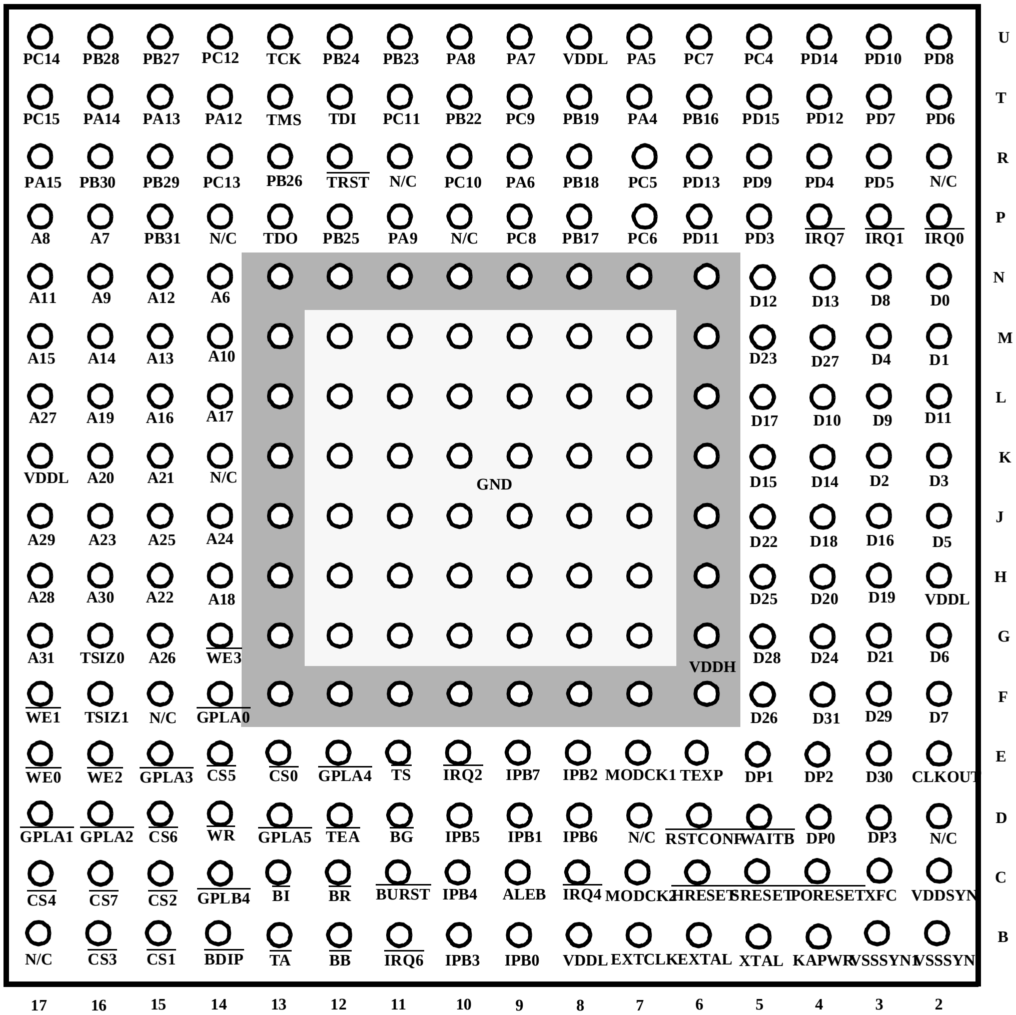
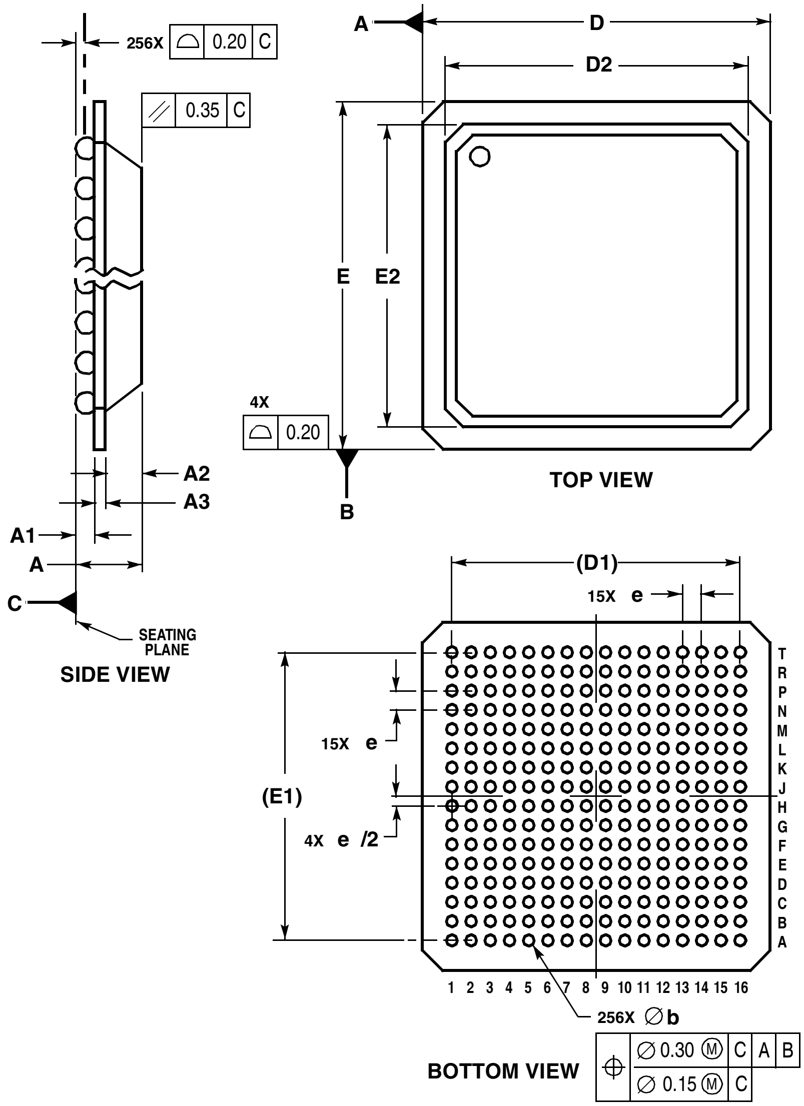


Figure 63. Pin Assignments for the PBGA (Top View)—JEDEC Standard

For more information on the printed circuit board layout of the PBGA package, including thermal via design and suggested pad layout, please refer to AN-1231/D, Plastic Ball Grid Array Application Note available from your local Freescale sales office.

Figure 64 shows the non-JEDEC package dimensions of the PBGA.



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND THE SEATING PLANE ARE

	MILLIMETERS	
DIM	MIN	MAX
A	1.91	2.35
A1	0.50	0.70
A2	1.12	1.22
A3	0.29	0.43
b	0.60	0.90
D	23.00 BSC	
D1	19.05 REF	
D2	19.00	20.00
E	23.00 BSC	
E1	19.05 REF	
E2	19.00	20.00
e	1.27 BSC	

Figure 64. Package Dimensions for the Plastic Ball Grid Array (PBGA)—non-JEDEC Standard

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